

# L9610

# PWM PowerMOS controller

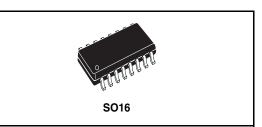
## Features

- High efficiency due to PWM control and PowerMOS driver
- Load dump protection
- Load power limitation
- External PowerMOS protection
- Limited output voltage slew rate

# Description

The L9610C is a monolithic integrated circuit working in PWM mode as controller of an external PowerMOS transistor in high side driver configuration.

#### Table 1 Device summary



Features of the device include controlled slope of the leading and trailing edge of the gate driving voltage, linear current limiting with protection timer, settable switching frequency io, TiLcompatible enable function, protection status ouput pin.

The device is mour led in SO16 micropackage.

x (?)

Table 1. Device summary		
Order code	Package	Packing
L9610C	SO16.	Tube
L9610C013TR	S.\016'\	Tape and reel

Obsolete Product(S)

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#### **Block diagram** 1

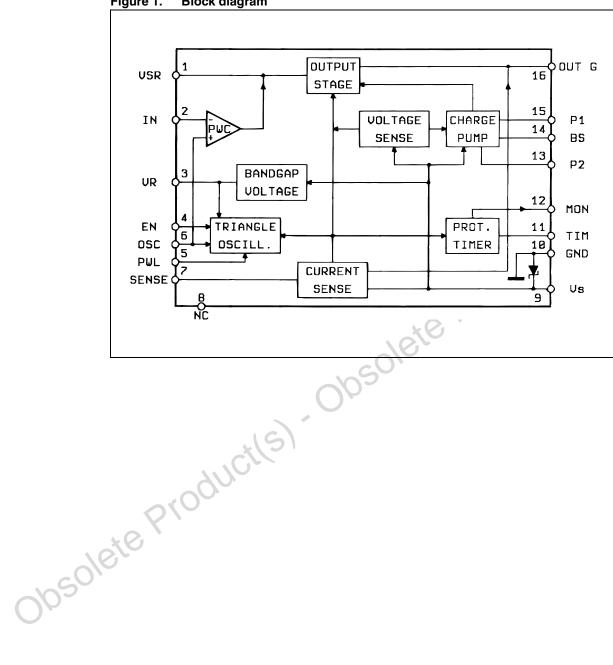


Figure 1. **Block diagram** 



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#### 2 **Pin description**

Figure 2.	<b>Pin connection</b>	(top view)
		(

		_
	1 U <sub>16</sub>	оит б
	2 15	D P1
	3 14	D BS
EN	4 13	D P2
PWL C	5 12	пом 🗋
osc 🗆	6 <sup>.</sup> 11	П ТІМ
	7 10	GND GND
	89	] Vs
l	-	

Table 2.	Pin	functions
Pin	Name	

	Pin	Name	Functions
	1	INT	A capacitor connected between this pin and Outg defines the gate voltage slew rate.
	2	IN	Analog input controlling the PWM ratio. The operating range of the input voltage is 0 to $V_{\rm R}$ .
	3	V <sub>R</sub>	Output of an internal voltage reference.
	4	EN	TTL compatible input for switching off the output.
	5	PWL	If this pin is connected to GND and $V_S > 13$ V, the duty cycle and the frequency $f_o$ are reduced : this allows to transfer a costant power to the load.
	6	O <sub>sc</sub>	Current sink and source stage connection of a triangle oscillator with definite voltage swing.
	7	IND	Input of an operational amplifier for short current sensing and regulation.
	8	NC	Not connected.
	9	VS	Common supply voltage input.
	10	GND	Common ground connection.
obsole	11	TIM	A capacitor connected between this pin and GND defines the protection delay time.
005	12	MON	Open collector monitoring output off the PowerMOS protection.
	13, 15	P2, P1	Connection for the charge pump capacitor.
	14	BS	The capacitor connected between this pin and the source of the PowerMOS allows to bootstrap the gate driving voltage.
	16	Out G	Output for driving the gate of the external PowerMOS.

#### **Electrical specification** 3

#### 3.1 Absolute maximum ratings

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
VS	Max. supply voltage	26	V
	Transient peak supply voltage ( $R_1 \ge 100 \Omega$ ):		
	Load dump:		
	5 ms $\leq$ $t_{rise} \leq$ 10 ms; $\tau_{f}$ Fall time constant = 100 ms; $R_{\text{source}} \geq$ 0.5 $\Omega$	60	V
	Field decay:		
	5 ms $\leq$ $t_{fall}$ $\leq$ 10 ms; $\tau r$ Rise time constant = 33 ms; $\textrm{R}_{\textrm{SOURCE}}$ $\geq$ 10 $\Omega$	-80	V
	Low energy spike: $t_{\text{rise}}$ =1 $\mu\sigma,$ $t_{\text{fall}}$ = 2 ms, R_{\text{source}} \ge 10 $\Omega$	±100	V
۱ <sub>s</sub>	Max. supply current (t < 300 ms)	0.3	Α
V <sub>IN</sub>	Input voltage	-0.3 < V <sub>IN</sub> < V <sub>S</sub> - 2.5	V
T <sub>J</sub> /T <sub>stg</sub>	Junction and storage temperature range	-55 to 150	°C
<b>3.2</b> Fable 4.	Thermal data		
Symbol	Parameter	Value	Unit

#### **Thermal data** 3.2

#### Table 4. Thermal data

Symbol	Parameter		Value	Unit
R <sub>th j-amb</sub>	Thermal resistance junction-alumina	Max.	50	°C/W
	.(5)			

#### 3.3 **Electrical characteristics**

#### Table 5. Electrical characteristcs

 $(T_{amb} = -40 \text{ °C to } 85 \text{ °C}; 6 \text{ V} < \text{Vs} < 16 \text{ V} \text{ unless otherwise specified})$ 

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Vs	Operating supply voltage		6		16	V
dq	Quiescent current			2.5	6	mA
V <sub>SC</sub>	Internal supply voltage clamp	I <sub>S</sub> =200 mA	28	32	36	V
V <sub>SH</sub>	Supply voltage high threshold		16	18.5	21	V
V <sub>SL</sub>	Supply voltage low threshold		4	5	6	V
V <sub>R</sub>	Reference voltage		3.3	3.5	3.7	V
I <sub>R</sub>	Reference current	$\Delta V_R \le 100 \text{ mV}$			1	mA
V <sub>INL</sub>	Input low threshold		0.13	0.15	0.2	$V_{IN}/V_{R}$

KF C Oscillator freq. constant(1)8002500KS Gate voltage slew rate constant(2)359KT Protection time delay constant(3)0.120.44VS Sense input volt.80100120VGON Gate driving volt. above VS US =16 V816VGONF VGONFGate voltage in off conditionIg=100 $\mu$ A1.2IN IN NENLInput current-5-1VENL Low enable voltage0.82.0IEN Enable input current22.0IEN Enable input current22.0IEN Low ratewithout CS0.5VMONsat Saturation voltage (pin 12)VMON= 2.5 mA1.5 <th>Symbol</th> <th>Parameter</th> <th>Test conditions</th> <th>Min.</th> <th>Тур.</th> <th>Max.</th> <th>Unit</th>	Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
K <sub>S</sub> constant $^{(L)}$ 3         5         9           K <sub>T</sub> Protection time delay constant         (3)         0.12         0.44           V <sub>Si</sub> Sense input volt.         80         100         120           V <sub>GON</sub> Gate driving volt. above V <sub>S</sub> Vs =16 V         8         16           V <sub>GOFF</sub> Gate voltage in off condition         I <sub>G</sub> =100 $\mu$ A         -5         -1           I <sub>IN</sub> Input current         -5         -1         0.8           V <sub>ENL</sub> Low enable voltage         2.0         0.8           V <sub>ENH</sub> High enable voltage         2.0         2           IEN         Enable input current         2.0         2	K <sub>F</sub>	Oscillator freq. constant	(1)	800		2500	nF/s
$V_{Si}$ Sense input volt.80100120 $V_{GON}$ Gate driving volt. above $V_S$ Vs =16 V816 $V_{GOFF}$ Gate voltage in off condition $I_G$ =100 µA1.2 $I_{IN}$ Input current-5-1 $V_{ENL}$ Low enable voltage0.80.8 $V_{ENH}$ High enable voltage2.02IENEnable input current22	K <sub>S</sub>	-	(2)	3	5	9	nFV/m
$V_{GON}$ Gate driving volt. above $V_S$ $Vs = 16 V$ 816 $V_{GOFF}$ Gate voltage in off condition $I_G = 100 \ \mu A$ -5-1 $I_{IN}$ Input current-5-10.8 $V_{ENL}$ Low enable voltage2.00.8 $V_{ENH}$ High enable voltage2.02IENEnable input current22	K <sub>T</sub>	Protection time delay constant	(3)	0.12		0.44	ms/nF
$V_{GOFF}$ Gate voltage in off condition $I_G=100 \ \mu A$ 1.2 $I_{IN}$ Input current-5-1 $V_{ENL}$ Low enable voltage0.8 $V_{ENH}$ High enable voltage2.0IENEnable input current2	V <sub>Si</sub>	Sense input volt.		80	100	120	mV
Input current-5-1V <sub>ENL</sub> Low enable voltage0.8V <sub>ENH</sub> High enable voltage2.0IENEnable input current2	V <sub>GON</sub>	Gate driving volt. above $V_S$	Vs =16 V	8		16	V
V <sub>ENL</sub> Low enable voltage     0.8       V <sub>ENH</sub> High enable voltage     2.0       IEN     Enable input current     2	V <sub>GOFF</sub>	Gate voltage in off condition	I <sub>G</sub> =100 μA			1.2	V
VENH     High enable voltage     2.0       IEN     Enable input current     2	I <sub>IN</sub>	Input current		-5	-1		μA
IEN Enable input current 2	V <sub>ENL</sub>	Low enable voltage				0.8	V
	V <sub>ENH</sub>	High enable voltage		2.0			V
SR         Slew rate         without Cs         0.5           V <sub>MONsat</sub> Saturation voltage (pin 12)         V <sub>MON = 2.5 mA</sub> 1.5           . f <sub>0</sub> = K <sub>F</sub> /C <sub>F</sub> . dV <sub>Q</sub> /(dt) = K <sub>S</sub> /C <sub>S</sub> 1.5           . dV <sub>g</sub> /(dt) = K <sub>S</sub> /C <sub>S</sub> . expression         . expression           . t <sub>prot</sub> = K <sub>T</sub> C <sub>T</sub> . expression         . expression	IEN	Enable input current				2	μA
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	SR	Slew rate	without C <sub>S</sub>		0.5		V/µs
$f_{0} = K_{F}/C_{F}$ $dV_{G}/(dt) = K_{S}/C_{S}$ $t_{prot} = K_{T}C_{T}$ Obsolution	V <sub>MONsat</sub>	Saturation voltage (pin 12)	$V_{MON=25 mA}$			1.5	V
osolete Product(S)	$dV_G/(dt)$ $t_{prot} = K_T$	= K <sub>S</sub> /C <sub>S</sub> C <sub>T</sub>	cO	etef			
osolete Prous	$dV_G/(dt)$ $t_{prot} = K_T$	= K <sub>S</sub> /C <sub>S</sub> C <sub>T</sub>	0050	etef			
osolete '	dV <sub>G</sub> /(dt) t <sub>prot</sub> = K <sub>T</sub>	- K <sub>S</sub> /C <sub>S</sub> .C <sub>T</sub>	5)-0050	etef			
05010	dV <sub>G</sub> /(dt) t <sub>prot</sub> = K <sub>T</sub>		5)-0050	etef			
	dV <sub>G</sub> /(dt) t <sub>prot</sub> = K <sub>T</sub>		(5)-0050	etef			
	dV <sub>G</sub> /(dt) t <sub>prot</sub> = K <sub>T</sub>		5)-0050	etef			

#### Table 5. Electrical characteristcs (continued)

(T<sub>amb</sub> = -40 °C to 85 °C; 6 V < Vs < 16 V unless otherwise specified)

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## 4 Functional description

#### 4.1 Pulse width comparator

A ground compatible comparator generates the PWM signal which controls the gate of the external PowerMOS. The slopes of the leading and trailing edges of the gate driving signal are defined by the external capacitor  $C_S$  according to :

$$dV_G/(dt) = K_S/C_S$$

This feature allows to optimize the switching speed for the power and RFI performance best suited for the application.

The lower limit of the duty cycle is fixed at 15 % of the ratio between the input and the reference voltage (see *Figure 3.*). Input voltages lower than this value disable the internal oscillator signal and therefore the gate driver.

### 4.2 Ground compatible triangle oscillator

The triangle oscillator provides the switching frequency  ${\rm f}_{\rm o}$  set by the external capacitor  ${\rm C}_{\rm F}$  according to:

 $f_0 = K_F / C_F$ 

If the pin PWL (power limitation) is connected to ground and Vs is higher than the PWL threshold voltage, the duty cycle and the  $f_0$  frequency are reduced: this allows to transfer a costant power to the load (see *Figure 4.*).

### 4.3 Timer and protection latch

When an overcurrent occurs, the device starts charging the external capacitor  $C_T$ ; the protection time is set according to :

 $t_{prot} = K_T \cdot C_T$ 

After the overcurrent protection time is reached, the PowerMOS is switched-off; this condition is latched by setting an internal flip-flop and is externally monitored by the low state of the MON pin.

To reset the latch the supply voltage has to fall below V<sub>SL</sub> or the device must be switched off.

4.4

## Under and overvoltage sense with load dump protection

The undervoltage detection feature resets the timer and switches off the output driving signal when the supply voltage is less than  $V_{SL}$ .

If the supply voltage exceeds the max operating supply voltage value, an internal comparator disables the charge pump, the oscillator and the external PowerMOS.

In both cases the thresholds are provided with suitable hysteresis values.

The load dump protection function allows the device to withstand, for a limited time, high overvoltages. It consists of an active clamping diode which limits the circuit supply voltage to



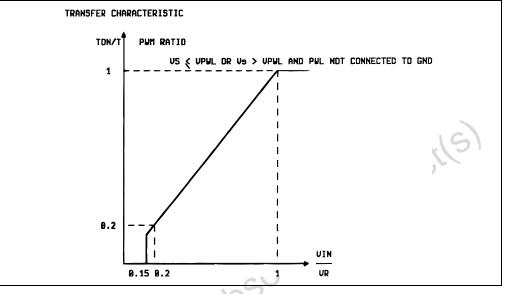
 $V_{CLAMP}$  and an external current limiting resistor  $R_1$ . The maximum pulse supply current (see abs. max. ratings is equal to 0.3 A. Therefore the maximum load dump voltage is given by:

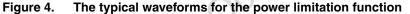
$$V_{\text{DUMP}} = V_{\text{SC}} + 0.3R_1$$

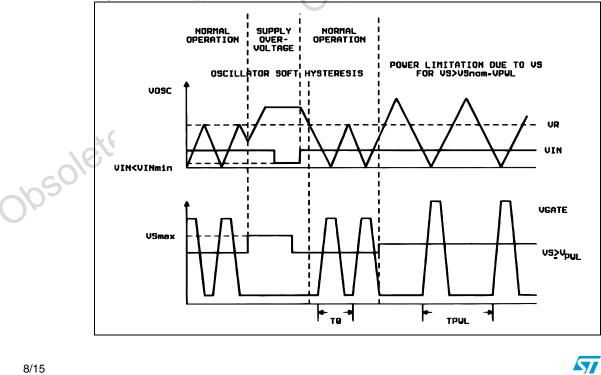
In this condition the gate of the PowerMOS is held at the GND pin potential and thus the load voltage is :

$$V_{L} = V_{S} - V_{CLAMP} - V_{GS}$$











#### 4.5 Short circuit current regulation

The maximum load current in the short circuit condition can be chosen by the value of the current sensing resistor  $R_S$  according to :

$$I_{SC} = V_{SI} / R_S$$

Two identical V<sub>S</sub> compatible comparators are provided to realize the short circuit protection.

After reaching the lower threshold voltage (typical value  $V_{SI}$ -10 mV), the first comparator enables the timer and the gate is driven with the full continuous pump voltage : when the upper threshold voltage value is reached the second comparator maintains the chosen  $I_{SC}$  driving the NMOS gate in continuous mode.

This function, showed in *Figure 5.*, speeds up the switch on phase for a lamp as a load.

#### 4.6 Bandgap voltage reference

The circuit provides a reference voltage which may be used as control input voltage through a resistive divider. This reference is protected against the short circuit current.

### 4.7 Charge pump

The charge pump circuit holds the N-MOS gate above the supply voltage during the ON phase. This circuit consists of an RC astable which drives a comparator with a push-pull output stage. The external charge pump capacitor  $C_P$  must be at least equal to the NMOS parasitic input capacitance.

For fast gate voltage variation  $C_P$  must be increased or the bootstrap function can be used. The bootstrap capacitor should be at least 10 times greater than the PowerMOS parasitic capacitance.

The charge pump voltage V<sub>PUMP</sub> can reach to :

 $V_{PUMP} = 2V_{S} - V_{BE} - V_{CESAT}$ The circuit is disabled if the supply voltage is higher than  $V_{SH}$ .

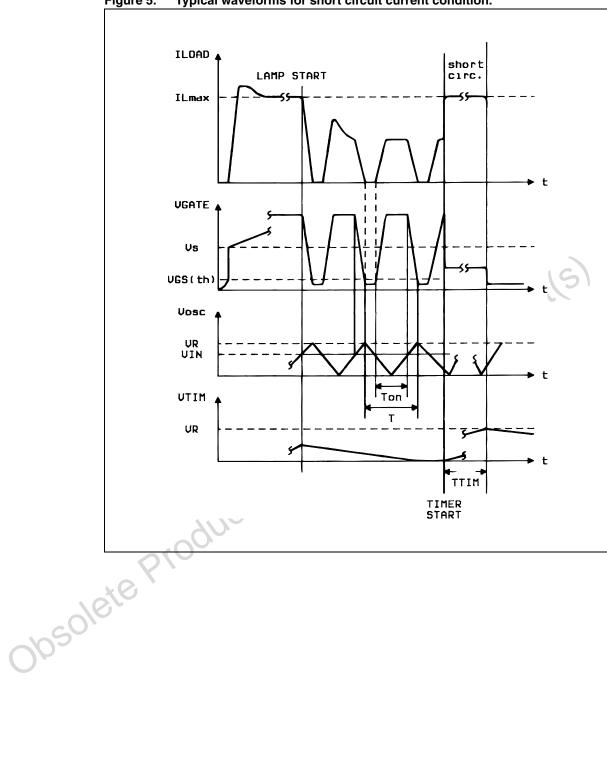
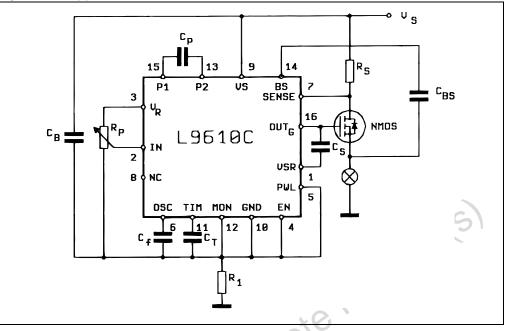


Figure 5. Typical waveforms for short circuit current condition.

# 5 Application circuit



#### Figure 6. Application circuit

1. All node voltages are referred to ground pin (GND).

2. The currents flowing in the arrow direction are assumed positive without  $C_{BS}$ :  $C_{P} = 1$  nF without  $C_{BS}$ :  $C_{BS}$  must be at least 10 times higher than the gate capacitance :  $C_{P} = 100$  pF.

# 5.1 Controlling a 120 W halogen lamp with the L9610C dimmer

The L9610C lamp dimmer is used to control the brightness of vehicle headlamps using H4 type lamps (see *Figure 7*.). With switch S1 open the full supply voltage is applied to the lamps: closing the switch it is a possible to reduce the average lamp voltage as desired:

$$VL = VS \frac{R3}{R2 + R3}$$

If pin 5 is connected to ground the average lamp voltage is constant, even for supply voltages in excess of 13 V.



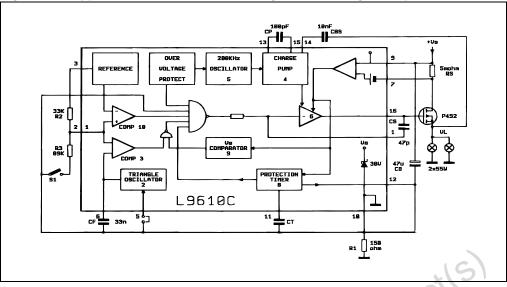


Figure 7. Application circuit with controlling a 120 W halogen lamp

The sensing resistor  $R_S$  and timing capacitor  $C_t$  should be dimensioned according to :

$$R_{S} = \frac{V_{Si}}{2Inom(@V_{S}= 14V)}$$
$$C_{t} = \frac{2 \times limitation time}{K_{T}}$$

In normal conditions ( $V_{CC}$  = 14 V, maximum brightness) the voltage drop across the sense resistor must be 50 mV. The current limiter intervenes attwice the nominal current,  $I_{nom}$ .

The timing capacitor  $C_t$  ( $V_{ct}$  = 3.5 V) must be chosen so that the delay before intervention is twice the duration of the current limitation at power-on.

The optimal value of the oscillator frequency, taking tolerances into account, must be slightly higher than the frequency at which lamp flicker is noticable (min 60 Hz).

The switching times are a compromise between possible EMI and switching power losses. The recommended value for  $C_s$  is 47 pF.

Jbsolete



# 6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>.

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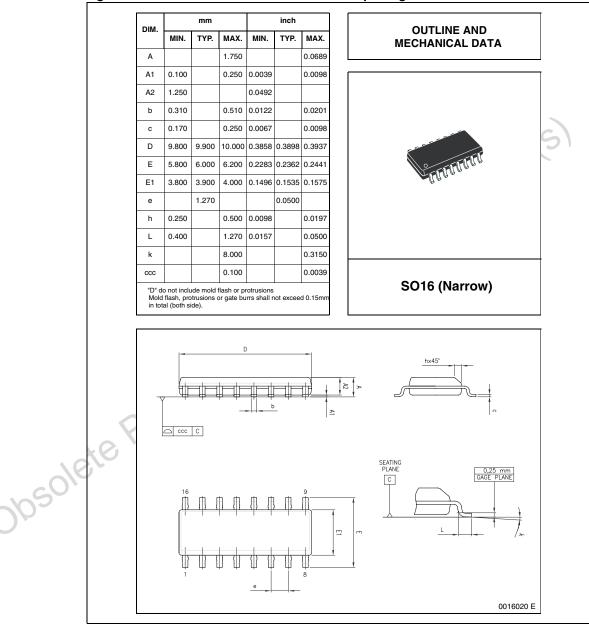


Figure 8. SO16 narrow mechanical data and package dimensions

# 7 Revision history

Table 6.	Document revision history
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Date	Revision	Changes
09-Oct-2000	1	Initial release.
18-Feb-2009	2	Document reformatted. Added <i>Table 1: Device summary on page 1.</i> Updated <i>Section 6: Package information on page 13.</i>

Obsolete Product(s). Obsolete Product(s)

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